

ProLight PG1C-5Lxx 5W Power LED Technical Datasheet Version: 2.2

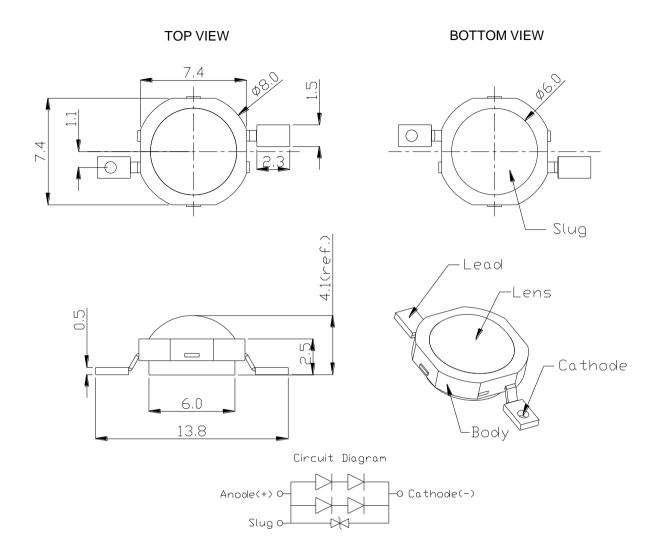
Features

- High flux per LED
- Various colors
- Good color uniformity
- Moisture senstivity level JEDEC 2a
 4 week floor life without reconditioning
- Low-temp. & lead free reflow soldering
- RoHS compliant
- More energy efficient than incandescent and most halogen lamps
- Low Voltage DC operated
- Instant light (less than 100ns)
- No UV
- Superior ESD protection

Typical Applications

- Reading lights (car, bus, aircraft)
- Portable (flashlight, bicycle)
- Uplighters/Downlighters
- Decorative/Entertainment
- Bollards/Security/Garden
- Cove/Undershelf/Task
- Indoor/Outdoor Commercial and Residential Architectural
- Automotive Ext (Stop-Tail-Turn, CHMSL, Mirror Side Repeat)
- LCD backlights

Emitter Mechanical Dimensions

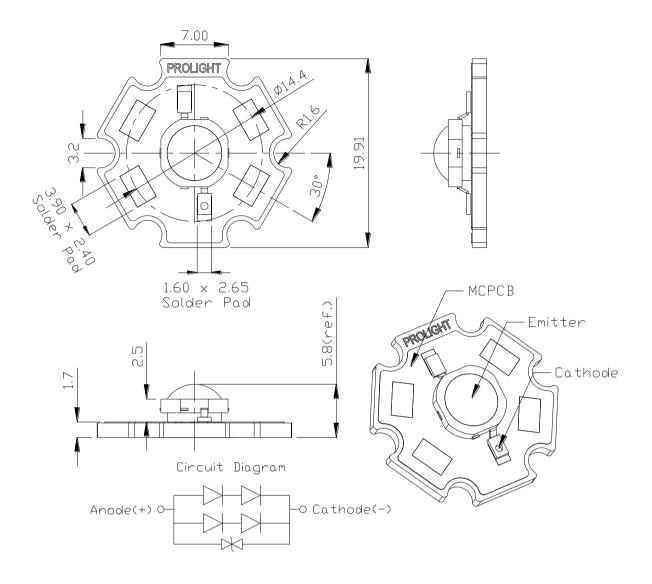


Notes:

- 1. The cathode side of the device is denoted by a hole in the lead frame.
- 2. Electrical insulation between the case and the board is required --- slug of device is not electrically neutral. Do not electrically connect either the anode or cathode to the slug.
- 3. Drawing not to scale.
- 4. All dimensions are in millimeters.
- 5. All dimendions without tolerances are for reference only.
- 6. Please do not bend the leads of the LED, otherwise it will damage the LED.
- 7. Please do not use a force of over 3kgf impact or pressure on the lens of the LED, otherwise it will cause a catastrophic failure.

*The appearance and specifications of the product may be modified for improvement without notice.

Star Mechanical Dimensions



Notes:

- 1. Slots in aluminum-core PCB for M3 or #4 mounting screw.
- 2. Electrical interconnection pads labeled on the aluminum-core PCB with "+" and "-" to denote positive and negative, respectively. All positive pads are interconnected, as are all negative pads, allowing for flexibility in array interconnection.
- 3. Drawing not to scale.
- 4. All dimensions are in millimeters.
- 5. All dimendions without tolerances are for reference only.
- 6. Please do not use a force of over 3kgf impact or pressure on the lens of the LED, otherwise it will cause a catastrophic failure.

*The appearance and specifications of the product may be modified for improvement without notice.

Radiation	Color	Part N	umber	Lumious Flux or Power	
Pattern	Color	Emitter	Star	Minimum	Typical
	White	PG1C-5LWE	PG1C-5LWS	369.9 lm	510 lm
	Warm White	PG1C-5LVE	PG1C-5LVS	369.9 lm	490 lm
	Red	PG1C-5LRE	PG1C-5LRS	129.5 lm	160 lm
Lambertian	Amber	PG1C-5LAE	PG1C-5LAS	129.5 lm	168 lm
	Green	PG1C-5LGE	PG1C-5LGS	249.6 lm	300 lm
	Blue	PG1C-5LBE	PG1C-5LBS	58.9 lm	76 lm
	Royal Blue	PG1C-5LDE	PG1C-5LDS	1400 mW	1750 mW

Flux Characteristics at 700mA, T_J = 25°C

• ProLight maintains a tolerance of ± 10% on flux and power measurements.

• Please do not drive at rated current more than 1 second without proper heat sink.

Electrical Characteristics at 700mA, $T_J = 25^{\circ}C$

Color	Fo Min.	orward Voltage V _F (Typ.	V) Max.	Thermal Resistance Junction to Slug (°C/ W)	Thermal Resistance Junction to Board (°C/ W)
White	5.7	6.8	8.2	3	5
Warm White	5.7	6.8	8.2	3	5
Red	3.5	4.4	6.2	3	5
Amber	3.5	4.4	6.2	3	5
Green	5.7	6.8	8.2	3	5
Blue	5.7	6.8	8.2	3	5
Royal Blue	5.7	6.8	8.2	3	5

• ProLight maintains a tolerance of ± 0.1 for Voltage measurements.

Color		ninant Wavelengtl olor Temperature	Total included Angle (degrees)	Viewing Angle (degrees)	
COIOI	Min.	Тур.	Max.	θ _{0.90V}	2 θ _{1/2}
White	4100 K	5500 K	10000 K	160	140
Warm White	2700 K	3300 K	4100 K	160	140
Red	613.5 nm	623 nm	631 nm	160	140
Amber	587 nm	592 nm	597 nm	160	140
Green	515 nm	525 nm	535 nm	160	140
Blue	455 nm	465 nm	475 nm	160	140
Royal Blue	450 nm	455 nm	460 nm	160	140

Optical Characteristics at 700mA, $T_J = 25^{\circ}C$

• ProLight maintains a tolerance of ± 1nm for dominant wavelength measurements.

• ProLight maintains a tolerance of \pm 5% for CCT measurements.

Absolute Maximum Ratings

Parameter	White/Warm White/Red/ Amber/Green/Blue/Royal Blue
DC Forward Current (mA)	700
Peak Pulsed Forward Current (mA)	1000 (less than 1/10 duty cycle@1KHz)
Average Forward Current (mA)	700
ESD Sensitivity	
(HBM per MIL-STD-883E Method 3015.7)	±4000V (Class III)
LED Junction Temperature ($^{\circ}$ C)	120°C
Operating Board Temperature	-40°C - 95°C
at Maximum DC Forward Current	-40 0 - 93 0
Storage Temperature	-40°C - 120°C
Soldering Temperature	235°C
Allowable Reflow Cycles	3
Reverse Voltage	Not designed to be driven in reverse bias

	Color	Bin Code	Minimum Radiometric Power (mW)	Maximum Radiometric Power (mW)	Available Color Bins
ĺ		х	1400	1650	All
	Royal Blue	Y	1650	2000	All
		Z	2000	2400	[1]

Radiometric Power Bin Structure

• ProLight maintains a tolerance of ± 10% on flux and power measurements.

• The flux bin of the product may be modified for improvement without notice.

Photometric Luminous Flux Bin Structure

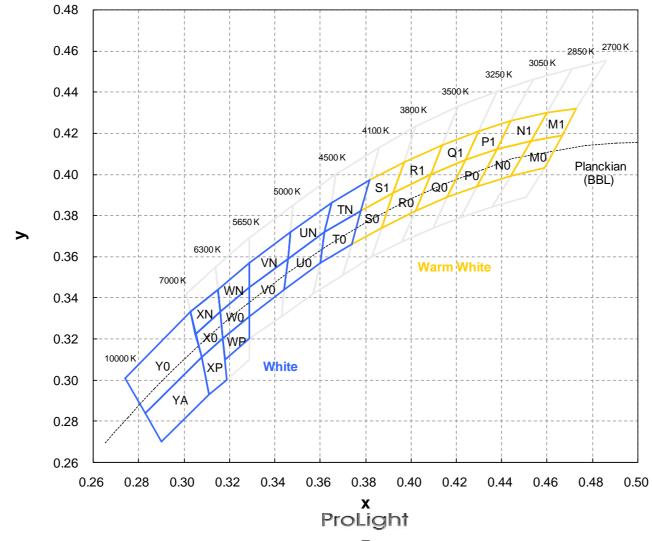
Color	Bin Code	Minimum Photometric Flux (Im)	Maximum Photometric Flux (Im)	Available Color Bins
	Z2	369.9	421.9	All
\A/bite	Z3	421.9	480	All
White	Z4	480	550	All
	Z5	550	630	[1]
	Z2	369.9	421.9	All
	Z3	421.9	480	All
Warm White	Z4	480	550	All
	Z5	550	630	[1]
	V2	129.5	147.7	All
Red	W1	147.7	168.4	All
	W2	168.4	192.0	[1]
	V2	129.5	147.7	All
Amber	W1	147.7	168.4	All
	W2	168.4	192.0	[1]
	Y1	249.6	284.5	All
Green	Y2	284.5	324.5	All
	Z1	324.5	369.9	[1]
	S2	58.9	67.2	A, 1 ^[1]
Blue	T1	67.2	76.6	A, 1 ^[1]
	T2	76.6	87.4	[1]

• ProLight maintains a tolerance of ± 10% on flux and power measurements.

• The flux bin of the product may be modified for improvement without notice.

• ^[1] The rest of color bins are not 100% ready for order currently. Please ask for quote and order possibility.

Color Bin



White and Warm White Binning Structure Graphical Representation

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Color Bins

White Bin Structure

Bin Code	x	у	Тур. ССТ (К)	Bin Code	x	у	Тур. ССТ (К)
	0.378	0.382			0.329	0.345	
то	0.374	0.366	4300	WN	0.316	0.333	5970
10	0.360	0.357	4000		0.315	0.344	0070
	0.362	0.372			0.329	0.357	
	0.382	0.397			0.329	0.331	
TN	0.378	0.382	4300	WP	0.329	0.320	5970
	0.362	0.372	4000		0.318	0.310	0070
	0.365	0.386			0.317	0.320	
	0.362	0.372			0.308	0.311	
UO	0.360	0.357	4750	X0	0.305	0.322	6650
00	0.344	0.344	4750	70	0.316	0.333	0000
	0.346	0.359			0.317	0.320	
	0.365	0.386		XN	0.305	0.322	
UN	0.362	0.372	4750		0.303	0.333	6650
ON	0.346	0.359	4750		0.315	0.344	0000
	0.347	0.372			0.316	0.333	
	0.329	0.331			0.308	0.311	
V0	0.329	0.345	5320	XP	0.317	0.320	6650
VO	0.346	0.359	5520	AF	0.319	0.300	0000
	0.344	0.344			0.311	0.293	
	0.329	0.345			0.308	0.311	
VN	0.329	0.357	5320	Y0	0.283	0.284	8000
VIN	0.347	0.372	5520	10	0.274	0.301	0000
	0.346	0.359			0.303	0.333	
	0.329	0.345			0.308	0.311	
W0	0.329	0.331	5070	VA	0.311	0.293	8000
000	0.317	0.320	0.320 5970 YA	0.290	0.270	0000	
	0.316	0.333			0.283	0.284	

• Tolerance on each color bin (x, y) is ± 0.01

Note: Although several bins are outlined, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all colors.

Color Bins

Warm White Bin Structure

Bin Code	x	У	Тур. ССТ (К)	Bin Code	x	У	Typ. CCT (K)
	0.453	0.416			0.409	0.400	
MO	0.444	0.399	2770	Q0	0.402	0.382	3370
IVIO	0.459	0.403	2110	QU	0.416	0.389	3370
	0.467	0.419			0.424	0.407	
	0.460	0.430			0.414	0.414	
M1	0.453	0.416	2770	Q1	0.409	0.400	3370
	0.467	0.419	2110	Q	0.424	0.407	3370
	0.473	0.432			0.430	0.421	
	0.438	0.412			0.392	0.391	
N0	0.429	0.394	2950	R0	0.387	0.374	3650
NO	0.444	0.399	2950		0.402	0.382	3030
	0.453	0.416			0.409	0.400	
	0.444	0.426			0.414	0.414	
N1	0.438	0.412	2950	R1	0.409	0.400	3650
	0.453	0.416	2350		0.392	0.391	3030
	0.460	0.430			0.397	0.406	
	0.424	0.407			0.392	0.391	
P0	0.416	0.389	3150	S0	0.387	0.374	3950
10	0.429	0.394	5150	00	0.374	0.366	5350
	0.438	0.412			0.378	0.382	
	0.430	0.421			0.397	0.406	
P1	0.424	0.407	3150	S1	0.392	0.391	3950
	0.438	0.412	0100	01	0.378	0.382	5350
	0.444	0.426			0.382	0.397	

 \bullet Tolerance on each color bin (x , y) is ± 0.01

Note: Although several bins are outlined, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all colors.

Color	Bin Code	Minimum Dominant Wavelength (nm)	Maximum Dominant Wavelength (nm)
Red	2	613.5	620.5
Reu	4	620.5	631.0
	2	587.0	589.5
A weeks a w	4	589.5	592.0
Amber	6	592.0	594.5
	7	594.5	597.0
	А	515	520
Crean	1	520	525
Green	2	525	530
	3	530	535
	А	455	460
Dhue	1	460	465
Blue	2	465	470
	3	470	475
Devial Dive	5	450	455
Royal Blue	6	455	460

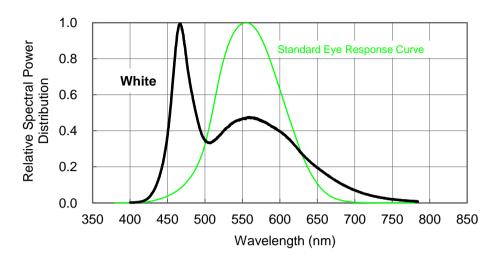
Dominant Wavelength Bin Structure

• ProLight maintains a tolerance of ± 1nm for dominant wavelength measurements.

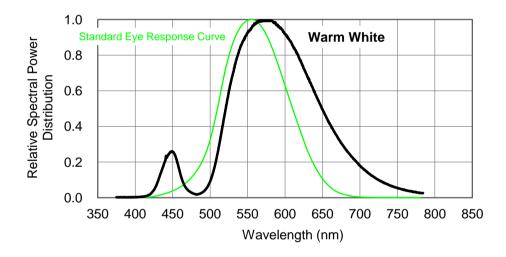
Note: Although several bins are outlined, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all colors.

Color Spectrum, $T_J = 25^{\circ}C$

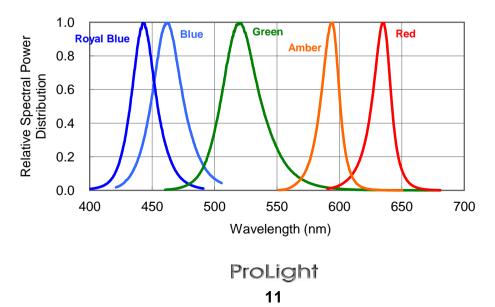
1. White



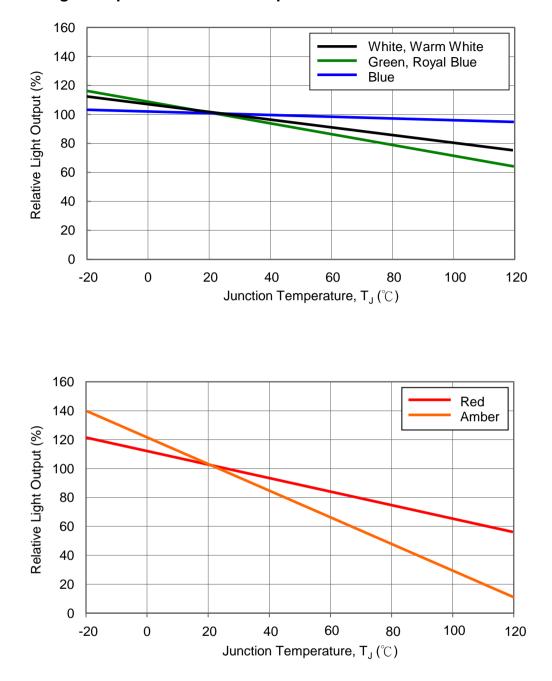
2. Warm White



3. Royal Blue Slue Green Amber Red



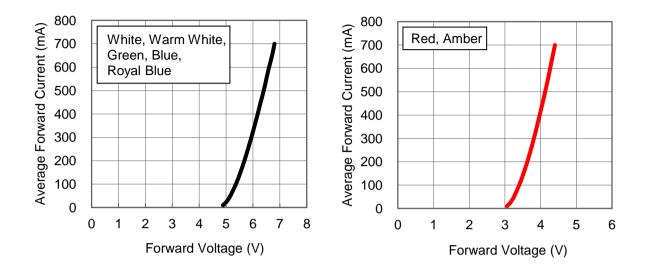
Light Output Characteristics



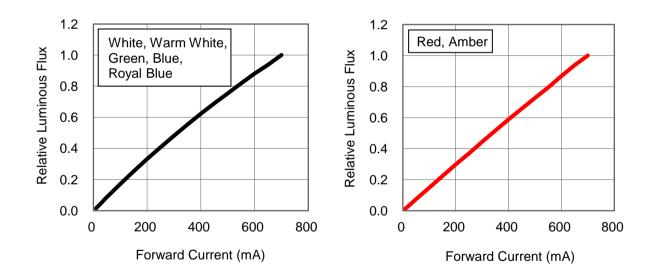
Relative Light Output vs. Junction Temperature at 700mA

Forward Current Characteristics, T_J = 25°C

1. Forward Voltage vs. Forward Current

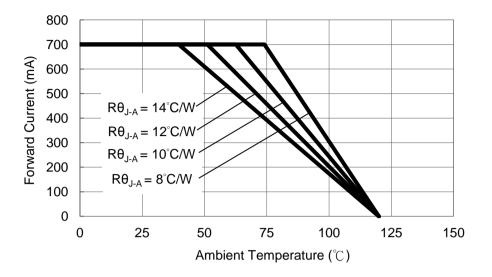


2. Forward Current vs. Normalized Relative Luminous Flux

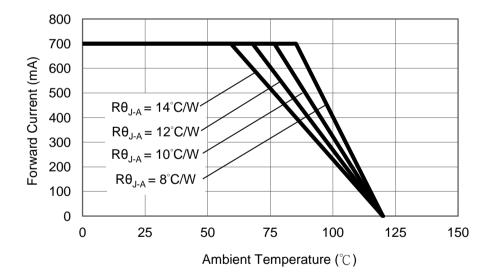


Ambient Temperature vs. Maximum Forward Current



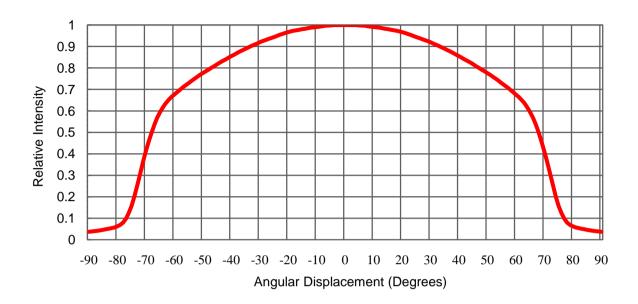


2. Red, Amber ($T_{JMAX} = 120^{\circ}C$)



Typical Representative Spatial Radiation Pattern

Lambertian Radiation Pattern



Moisture Sensitivity Level - JEDEC 2a

			Soak Requirements				
Level	Floo	Floor Life		Standard		Accelerated Environment	
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions	
20	4 weeks	≤30°C /	696 15/0	30°C /	120 +1/-0	60°C /	
2a	4 weeks	60% RH	696 +5/-0	60% RH	120 +1/-0	60% RH	

• The standard soak time includes a default value of 24 hours for semiconductor manufature's exposure time (MET) between bake and bag and includes the maximum time allowed out of the bag at the distributor's facility.

• Table below presents the moisture sensitivity level definitions per IPC/JEDEC's J-STD-020C.

			Soak Requirements				
Level	Floo	r Life	Stan	dard	Accelerated	Environment	
	Time	Conditions	Time (hours)	Conditions	Time (hours)	Conditions	
1	Unlimited	≤30°C /	168 +5/-0	85°C /	NA	NA	
1	Oninnited	85% RH	100 +3/-0	85% RH		N/A	
2	1 year	≤30°C /	168 +5/-0	85°C /	NA	NA	
2	i year	60% RH	100 +5/-0	60% RH	NA	NA .	
2a	4 weeks	≤30°C /	696 +5/-0	30°C /	120 +1/-0	60°C /	
Za	4 WEEKS	60% RH	090 +5/-0	60% RH	120 +1/-0	60% RH	
3	168 hours	≤30°C /	192 +5/-0	30°C /	40 +1/-0	60°C /	
5	100 110013	60% RH	192 +5/-0	60% RH	40 + 1/-0	60% RH	
4	72 hours	≤30°C /	96 +2/-0	30°C /	20 +0.5/-0	60°C /	
4	72 110013	60% RH	90 +2/-0	60% RH	20 +0.3/-0	60% RH	
5	48 hours	≤30°C /	72 +2/-0	30°C /	15 +0.5/-0	60°C /	
5	40 110013	60% RH	12 +2/-0	60% RH	15 +0.5/-0	60% RH	
5a	24 hours	≤30°C /	48 +2/-0	30°C /	10 +0.5/-0	60°C /	
Ja	24 110015	60% RH	40 +2/-0	60% RH	10 +0.5/-0	60% RH	
6	Time on Label	≤30°C /	Time on Label	30°C /	NA	NA	
0	(TOL)	60% RH	(TOL)	60% RH			

Qualification Reliability Testing

Stress Test	Stress Conditions	Stress Duration	Failure Criteria
Room Temperature	25°C, I _F = max DC (Note 1)	1000 hours	Note 2
Operating Life (RTOL)		Tood hours	Note 2
Wet High Temperature	85°C/60%RH, I _F = max DC (Note 1)	1000 hours	Note 2
Operating Life (WHTOL)		1000 110013	Note 2
Wet High Temperature	85°C/85%RH, non-operating	1000 hours	Note 2
Storage Life (WHTSL)	85 C/65 %KH, Hon-operating	1000 110013	Note 2
High Temperature	110°C, non-operating	1000 hours	Note 2
Storage Life (HTSL)	TO C, non-operating	1000 110015	Note 2
Low Temperature	-40°C, non-operating	1000 hours	Note 2
Storage Life (LTSL)	-40 C, non-operating	TOOUTIOUTS	Note 2
Non-operating	-40°C to 120°C, 30 min. dwell,		Note 2
Temperature Cycle (TMCL)	<5 min. transfer	200 cycles	NOLE 2
Non-operating	-40°C to 120°C, 20 min. dwell,	200 cycles	Note 2
Thermal Shock (TMSK)	<20 sec. transfer	200 cycles	Note 2
Mechanical Shock	1500 G, 0.5 msec. pulse,		Note 3
Mechanical Shock	5 shocks each 6 axis		Note 5
Natural Drop	On concrete from 1.2 m, 3X		Note 3
Variable Vibration	10-2000-10 Hz, log or linear sweep rate,		Note 2
Frequency	20 G about 1 min., 1.5 mm, 3X/axis		Note 3
Solder Heat Resistance (SHR)	260°C ± 5°C, 10 sec.		Note 3
Colderability	Steam age for 16 hrs., then solder dip		Solder coverage
Solderability	at 260°C for 5 sec.		on lead

Notes:

1. Depending on the maximum derating curve.

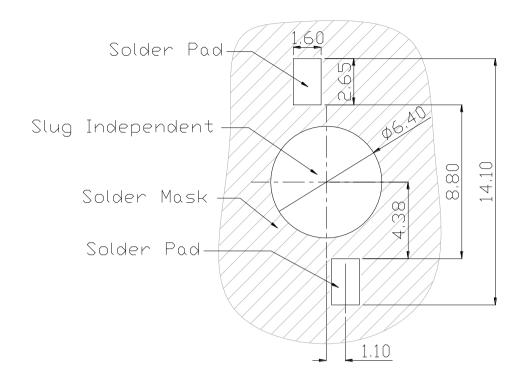
2. Criteria for judging failure

Item	Test Condition	Criteria for Judgement	
		Min.	Max.
Forward Voltage (V _F)	I _F = max DC		Initial Level x 1.1
Luminous Flux or Radiometric Power (Φ_V)	I _F = max DC	Initial Level x 0.7	
Reverse Current (I _R)	$V_R = 5V$		50 µA

* The test is performed after the LED is cooled down to the room temperature.

3. A failure is an LED that is open or shorted.

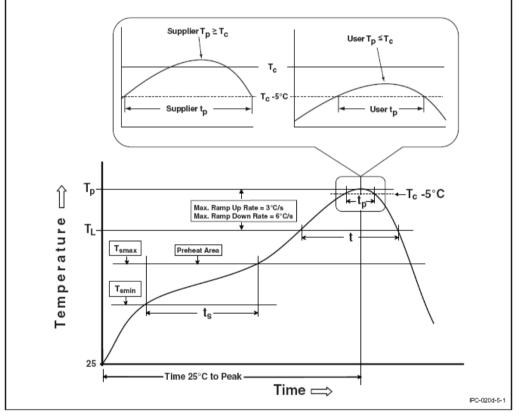
Recommended Solder Pad Design



- All dimensions are in millimeters.
- Electrical isolation is required between Slug and Solder Pad.

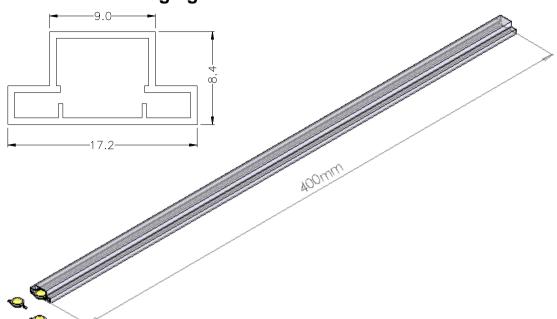
Reflow Soldering Condition

Profile Feature	Sn-Pb Eutectic Assembly	Low-Temp. & Pb-Free Assembly (58Bi-42Sn Eutectic Alloy)	
Preheat & Soak			
Temperature min (T _{smin})	100 °C	90 °C	
Temperature max (T _{smax})	150 °C	120 °C	
Time (T _{smin} to T _{smax})	60-120 seconds	60-120 seconds	
Average Ramp-Up Rate (T_{smax} to T_{P})	3 °C / second max.	2 °C / second max.	
Liquidous temperature (T _L)	183°C	138°C	
Time at liquidous (t _L)	60-150 seconds	20-50 seconds	
Peak package body temperature (T _P)	235°C	185°C	
Time (t_P) within 5°C of the specified	20 accordo	20 seconds	
classification temperature (T _C)	20 seconds		
Average ramp-down rate (T_P to T_{smax})	6 °C/second max.	3 °C/second max.	
Time 25°C to Peak Temperature	6 minutes max.	4 minutes max.	

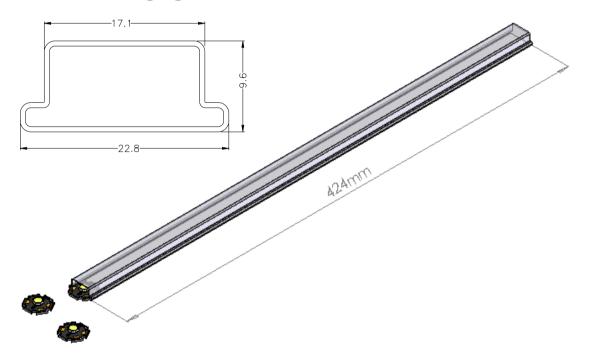


- All temperatures refer to topside of the package, measured on the package body surface.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a heat plate should be used. It should be confirmed beforehand whether the characteristics of LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than three times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

Emitter Tube Packaging



Star Tube Packaging



Notes:

- 1. Emitter 50 pieces per tube and Star 20 pieces per tube.
- 2. Drawing not to scale.
- 3. All dimensions are in millimeters.
- 4. All dimendions without tolerances are for reference only.
- **Please do not open the moisture barrier bag (MBB) more than one week. This may cause the leads of LED discoloration. We recommend storing ProLight's LEDs in a dry box after opening the MBB. The recommended storage conditions are temperature 5 to 30°C and humidity less than 40% RH.

Precaution for Use

Storage

Please do not open the moisture barrier bag (MBB) more than one week. This may cause the leads of LED discoloration. We recommend storing ProLight's LEDs in a dry box after opening the MBB. The recommended storage conditions are temperature 5 to 30°C and humidity less than 40% RH. It is also recommended to return the LEDs to the MBB and to reseal the MBB.

- The slug is is not electrically neutral. Therefore, we recommend to isolate the heat sink.
- Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temperature after soldering.
- Please avoid rapid cooling after soldering.
- Components should not be mounted on warped direction of PCB.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a heat plate should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When cleaning is required, isopropyl alcohol should be used.
- When the LEDs are illuminating, operating current should be decide after considering the package maximum temperature.
- The appearance, specifications and flux bin of the product may be modified for improvement without notice. Please refer to the below website for the latest datasheets. http://www.prolightopto.com/

Handling of Silicone Lens LEDs

Notes for handling of silicone lens LEDs

- Please do not use a force of over 3kgf impact or pressure on the silicone lens, otherwise it will cause a catastrophic failure.
- The LEDs should only be picked up by making contact with the sides of the LED body.
- Avoid touching the silicone lens especially by sharp tools such as Tweezers.
- Avoid leaving fingerprints on the silicone lens.
- Please store the LEDs away from dusty areas or seal the product against dust.
- When populating boards in SMT production, there are basically no restrictions regarding the form of the pick and place nozzle, except that mechanical pressure on the silicone lens must be prevented.
- Please do not mold over the silicone lens with another resin. (epoxy, urethane, etc)



